

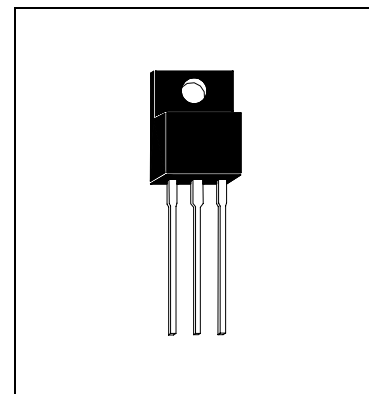


HSDF313

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HSDF313 is designed for use in general purpose amplifier and switching applications.



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -50~+150°C
Junction Temperature +150°C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 20 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 60 V
BVCEO Collector to Emitter Voltage 60 V
BVEBO Emitter to Base Voltage 5 V
IC Collector Current 3 A

Characteristics (Ta=25°C)

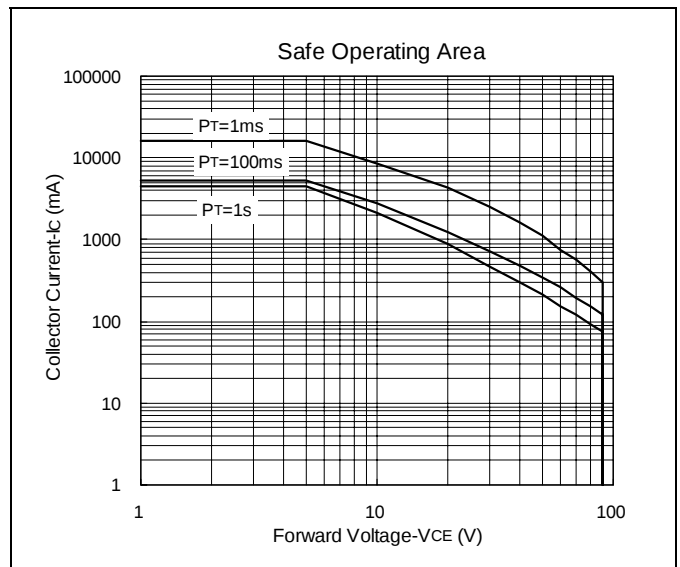
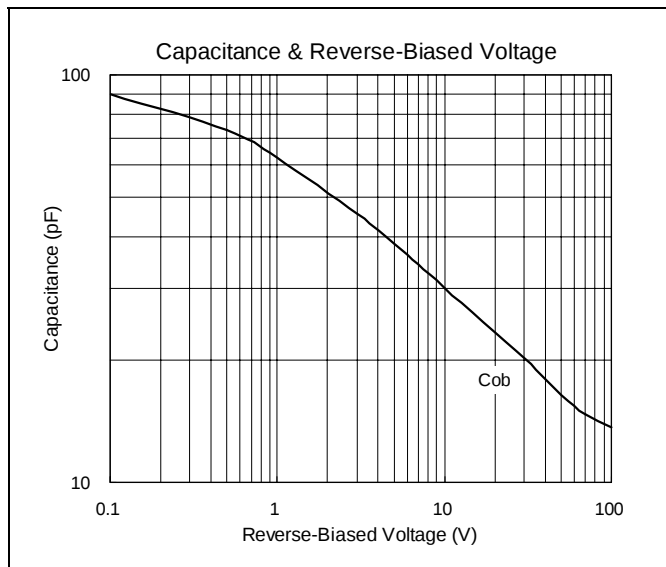
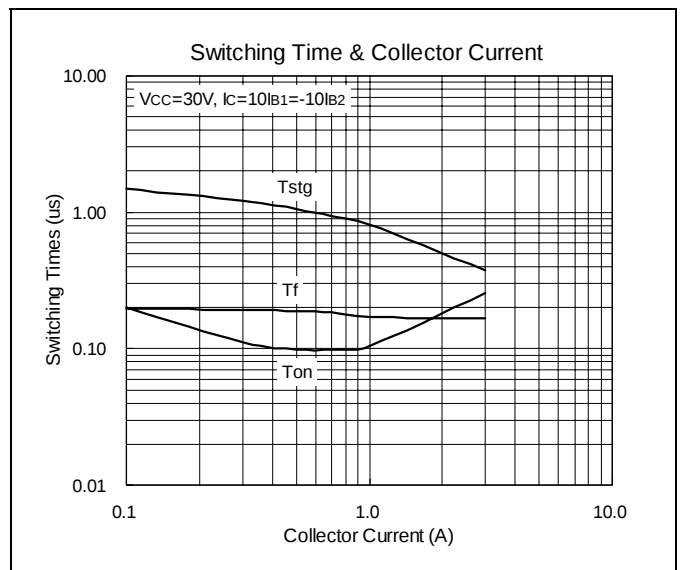
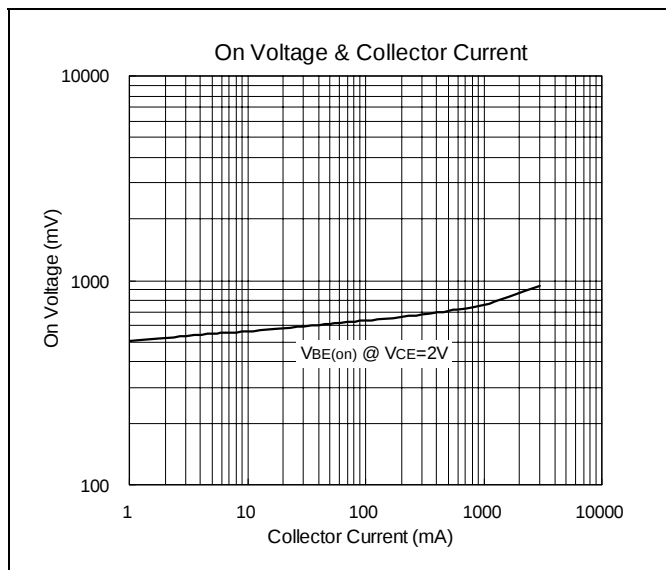
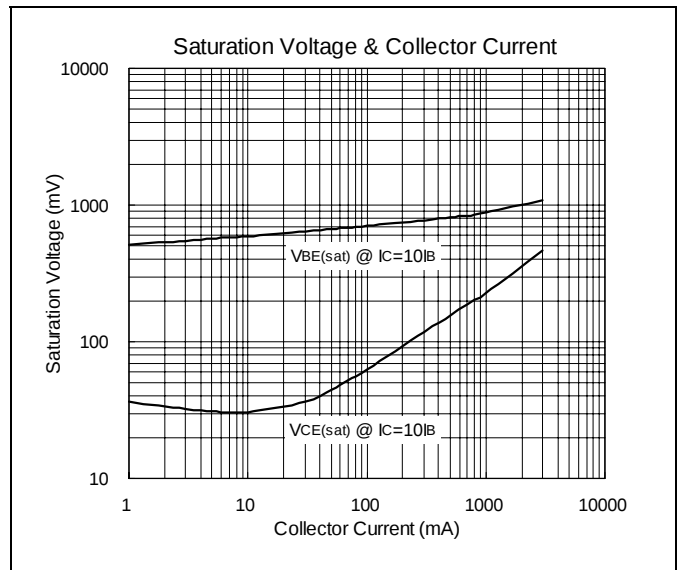
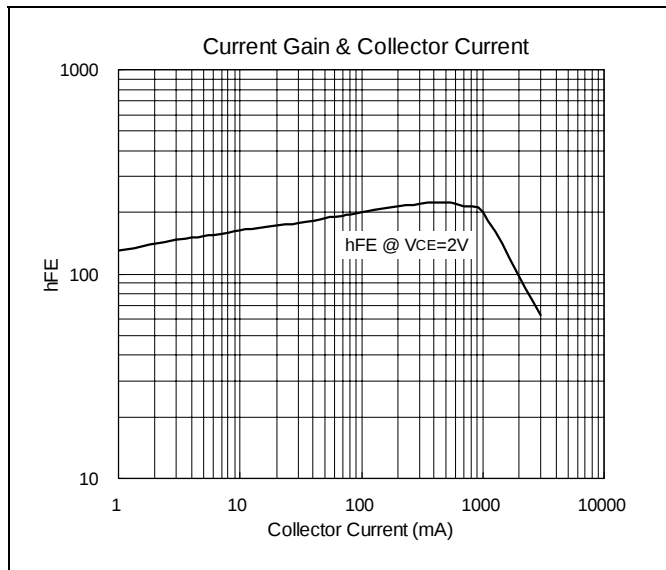
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	60	-	-	V	IC=1mA
BVCEO	60	-	-	V	IC=10mA
BVEBO	5	-	-	V	IE=100uA
ICBO	-	-	0.1	mA	VCB=20V
ICEO	-	-	5	mA	VCE=60V
IEBO	-	-	1	mA	VEB=4V
VCE(sat)	-	-	1	V	IC=2A, IB=0.2A
VBE(on)	-	-	1.5	V	IC=1A, VCE=2V
hFE1	40	-	320		IC=1A, VCE=2V
HFE2	40	-	-		IC=0.1A, VCE=2V

Classification Of hFE1

Rank	C	D	E	F
hFE	40-80	60-120	100-200	160-320

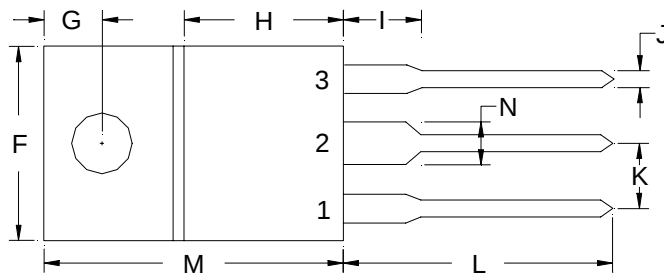
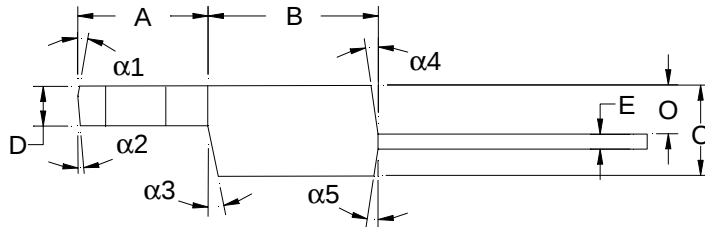


Characteristics Curve



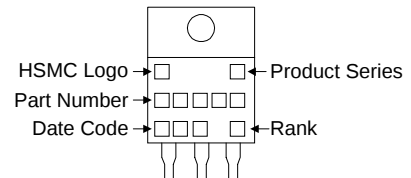


TO-220FP Dimension



3-Lead TO-220FP Plastic Package
HSMC Package Code : F

Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2480	0.2520	6.30	6.40	K	-	*0.1004	-	*2.55
B	0.3386	0.3425	8.60	8.70	L	0.5118	0.5906	13.00	15.00
C	0.1673	0.1870	4.25	4.75	M	0.5886	0.5925	14.95	15.05
D	0.1043	0.1083	2.65	2.75	N	-	*0.0669	-	*1.70
E	0.0230	0.0242	0.58	0.61	O	0.1098	0.1114	2.79	2.83
F	0.3980	0.4039	10.11	10.26	1	-	-2°	-	*2°
G	0.1083	0.1122	2.75	2.85	2	-	*5°	-	*5°
H	0.3386	0.3425	8.60	8.70	3	-	*15°	-	*15°
I	-	*0.1496	-	*3.80	4	-	*5°	-	*5°
J	-	*0.0236	-	*0.60	5	-	*5°	-	*5°

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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